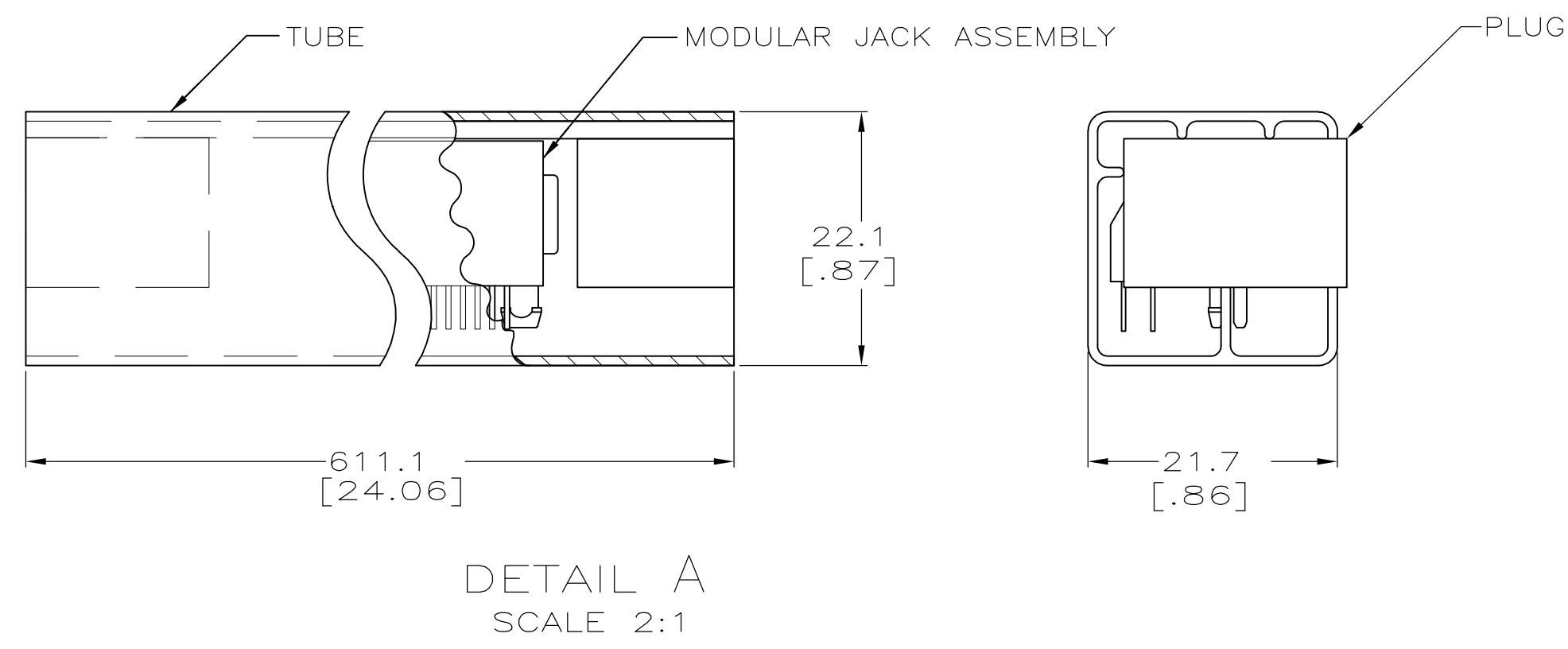


RECOMMENDED PRINTED CIRCUIT BOARD LAYOUT (COMPONENT SIDE)



- MATERIAL:
HOUSING - HTN MOLDING COMPOUND, UL 94V-0, BLACK
TERMINAL - 0.36[.014] THICK PHOS-BRONZE PLATED WITH 1.27μm[.000050] MINIMUM THICK HARD GOLD IN LOCALIZED GOLD PLATE AREA AND 3.81μm[.000150] MINIMUM THICK MATTE TIN IN SOLDER AREA OVER 1.27μm[.000050] THICK MINIMUM NICKEL UNDERPLATE.
SHIELD - 0.25[.010] THICK COPPER ALLOY PLATED WITH 3.0μm[.000120] MINIMUM REFLOWED TIN
- CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68, SUBPART F.
- DIMENSION MEASURED ALONG FRONT EDGE OF MATING FACE
- PACKAGED 31 ASSEMBLIES PER TUBE WITH BOTH ENDS PLUGGED (SEE DETAIL A)

6368018-1
PART NUMBER

THIS DRAWING IS A CONTROLLED DOCUMENT.		DWN L. VARELA - DOCK5 15JUN2005	Tyco Electronics Corporation Harrisburg, PA 17105-3608	
DIMENSIONS: mm [INCHES]		CHK J. WESTMAN 15JUN2005	Tyco Electronics	
TOLERANCES UNLESS OTHERWISE SPECIFIED:		APVD S. FLICKINGER 15JUN2005	NAME MODULAR JACK ASSEMBLY, 8 POSITION, RIGHT ANGLE, LOW PROFILE, SHIELDED, PANEL GROUND, LOW INSERT FORCE (IR)	
0 PLC ± -		PRODUCT SPEC	108-1163	
1 PLC ± -		APPLICATION SPEC	114-2048	
2 PLC ± 0.13[.005]		SIZE	A1	
3 PLC ± -		CAGE CODE	6368018	
4 PLC ± -		DRAWING NO	C-6368018	
ANGLES ± -		WEIGHT	-	
MATERIAL SEE NOTE 1		FINISH SEE NOTE 1	CUSTOMER DRAWING	
		SCALE	4:1	
		SHEET	1 OF 1	
		REV	B	